MBRS3200T3G, NRVBS3200T3G

Surface Mount Schottky Power Rectifier

This device employs the Schottky Barrier principle in a large area metal-to-silicon power diode. State-of-the-art geometry features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency rectification, or as free wheeling and polarity protection diodes in surface mount applications where compact size and weight are critical to the system.

Features

- Small Compact Surface Mountable Package with J-Bend Leads
- Rectangular Package for Automated Handling
- Highly Stable Oxide Passivated Junction
- Very High Blocking Voltage 200 V
- 175°C Operating Junction Temperature
- Guard-Ring for Stress Protection
- NRVB Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements: AEC-Q101 Qualified and PPAP Capable
- All Packages are Pb-Free*

Mechanical Charactersistics

- Case: Epoxy, Molded, Epoxy Meets UL 94, V-0
- Weight: 95 mg (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Cathode Polarity Band
- Device Meets MSL 1 Requirements
- ESD Ratings:
 - Machine Model = A
 - ♦ Human Body Model = 1C



ON Semiconductor®

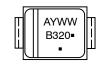
http://onsemi.com

SCHOTTKY BARRIER RECTIFIER 3.0 AMPERE 200 VOLTS



SMB CASE 403A

MARKING DIAGRAM



B320	= Specific Device Code
А	= Assembly Location
Y	= Year
WW	= Work Week
•	= Pb-Free Package
(Note: N	licrodot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]	
MBRS3200T3G	SMB (Pb-Free)	2,500 / Tape & Reel	
NRVBS3200T3G	SMB (Pb-Free)	2,500 / Tape & Reel	

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	200	V
Average Rectified Forward Current (T_L = 150 °C)	I _{F(AV)}	3.0	А
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I _{FSM}	100	А
Operating Junction Temperature	TJ	–65 to +175	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Lead (Note 1)	R _{θJL}	13	°C/W
Thermal Resistance, Junction-to-Ambient (Note 2)	R _{θJA}	62	

ELECTRICAL CHARACTERISTICS

	VF	0.84 0.86 0.59	V
Maximum Instantaneous Reverse Current (Note 3) (Rated dc Voltage, $T_J = 25^{\circ}$ C) (Rated dc Voltage, $T_J = 150^{\circ}$ C)	I _R	1.0 5.0	mA mA

1. Minimum pad size (0.108 \times 0.085 inch) for each lead on FR4 board.

2. 1 inch square pad size (1 \times 0.5 inch) for each lead on FR4 board.

3. Pulse Test: Pulse Width = 300 μ s, Duty Cycle \leq 2.0%.

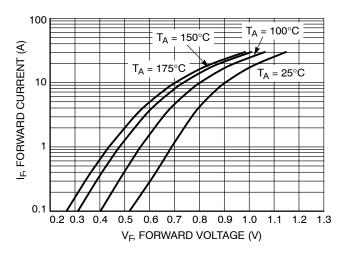


Figure 1. Typical Forward Voltage

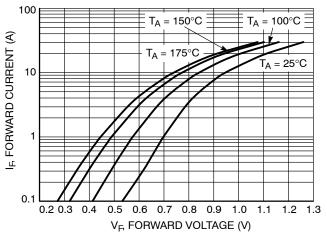
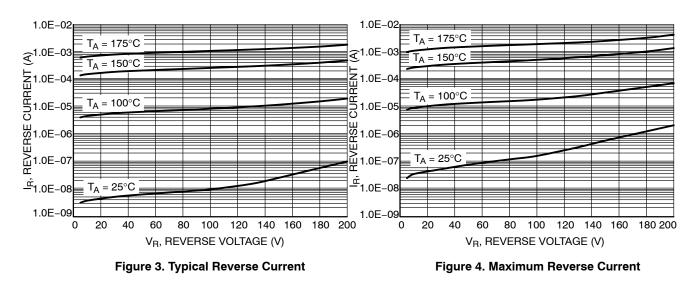


Figure 2. Maximum Forward Voltage

MBRS3200T3G, NRVBS3200T3G



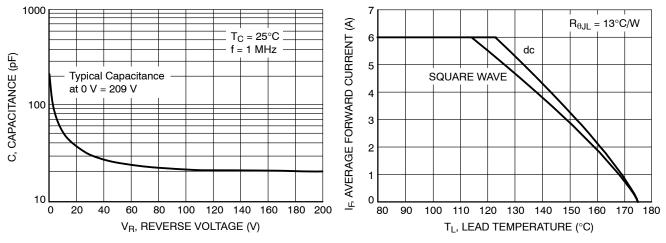
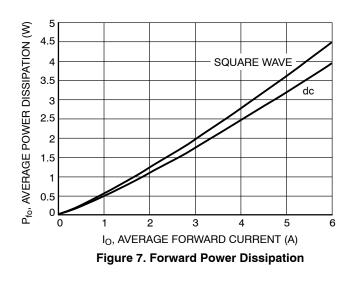


Figure 5. Typical Capacitance

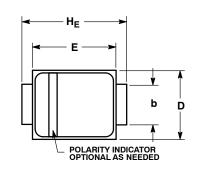
Figure 6. Current Derating – Lead

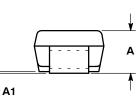


MBRS3200T3G, NRVBS3200T3G

PACKAGE DIMENSIONS

SMB CASE 403A-03 **ISSUE J**





NOTES 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION & SHALL BE MEASURED WITHIN DIMENSION L1.

3.56

4.32

5.44

1.02

0.51 RE

D

E HE

L

3.30

4.06

5.21

0.76

MILLIMETERS INCHES DIM MIN NOM MAX MIN NOM MAX 2.47 1.95 0.091 0.097 Α 2.30 0.077 A1 0.05 0.10 0.20 0.002 0.004 0.008 b 1.96 2.03 2.20 0.077 0.080 0.087 0.23 0.009 С 0.15 0.31 0.006 0.012

3.95

4.60

5.60

1.60

0.130

0.160

0.205

0.140

0.170

0.214

0.020 REF

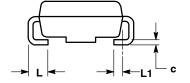
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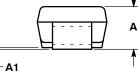
0.156

0.181

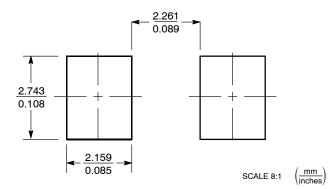
0.220

0.063





SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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